

## **30V P-Channel Trench MOSFET**

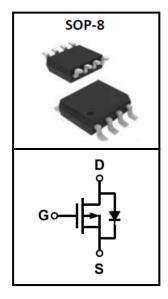
### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

### **APPLICATIONS**

- Load switch
- Uninterruptible Power Supply (UPS)
- Pulse Width Modulation(PWM)





Device Marking and Package Information				
Device	evice Package			
CTS03P015	SOP-8	CTS03P015		

<b>Absolute Maximum Ratings</b> at $T_j = 25^{\circ}$ C unless otherwise noted					
Parameter		Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)		V <sub>DSS</sub>	-30	V	
Drain Current-Continuous(Tc=25°C)	(note1)	ı	-12	Α	
Drain Current-Continuous(Tc=100°C)	(note1)	I <sub>D</sub>	-49		
Gate Source Voltage		$V_{GSS}$	±20	V	
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	125	mJ	
Power Dissipation $T_C = 25^{\circ}C$	(note4)	$P_D$	1.5	W	
Operating Junction and Storage Temperature Range		$T_J, T_stg$	-55~+175	°C	

Thermal Characteristics				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient (t≤10S) (no	ote1)	$R_{\scriptscriptstyle{\thetaJA}}$	41	°C/W



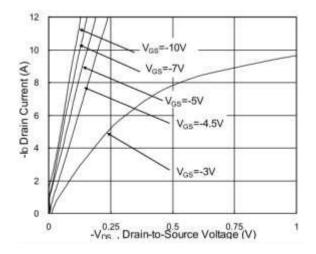
			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -24V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			-1	uA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1.0	-1.6	-3.0	V	
Drain-Source On-Resistance (note2)	Ь	V <sub>GS</sub> = -10V, I <sub>D</sub> = -10A			15	mΩ	
Diam-Source On-Resistance (notez)	R <sub>DS(on)</sub>	$V_{GS} = -4.5V, I_{D} = -10A$			25	mΩ	
Dynamic							
Input Capacitance	$C_{iss}$	$V_{GS} = 0V$ ,		2215		pF	
Output Capacitance	$C_{oss}$	$V_{DS} = -15V$ ,		310			
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0MHz		237			
Total Gate Charge (4.5V)	$Q_g$			20			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15V, I_{D} = -10A,$ $V_{GS} = -4.5V$		5.1		nC	
Gate-Drain Charge	$Q_{gd}$	- 65		7.3			
Turn-on Delay Time	t <sub>d(on)</sub>			33.8			
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = -15V, R_{L} = 15\Omega$		35.6			
Turn-off Delay Time	t <sub>d(off)</sub>	$V_{GS} = -10V, R_G = 2.5\Omega$ $I_D = -1A$		73		ns	
Turn-off Fall Time	t <sub>f</sub>			11			
Body Diode Characteristics							
Source-Drain Current(Body Diode)	I <sub>SD</sub>				-12	A	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = -1.7A$ , $V_{GS} = 0V$			-1.2	V	

#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width≦300us , duty cycle≦2%
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- $5. \ The \ data \ is \ theoretically \ the \ same \ as \ ID \ and \ IDM \ , \ in \ real \ applications \ , \ should \ be \ limited \ by \ total \ power \ dissipation.$



## **Typical Characteristics** $T_J = 25$ °C, unless otherwise noted



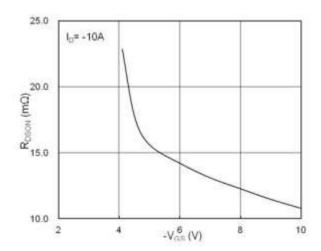
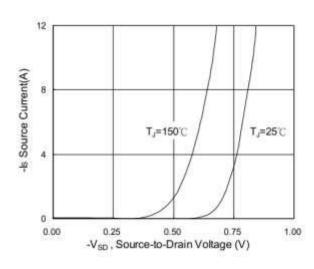


Fig.1 Typical Output Characteristics





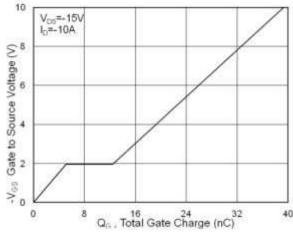


Fig.3 Forward Characteristics of Reverse

1.5 Normalized Visiting -50 T<sub>J</sub>, Junction Temperature (°C )100 150

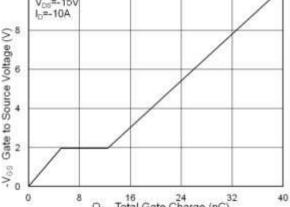
Normalized On Resistance

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized VGS(th) vs. TJ

Fig.6 Normalized RDSON vs. TJ

T<sub>J</sub>, Junction Temperature (°C)

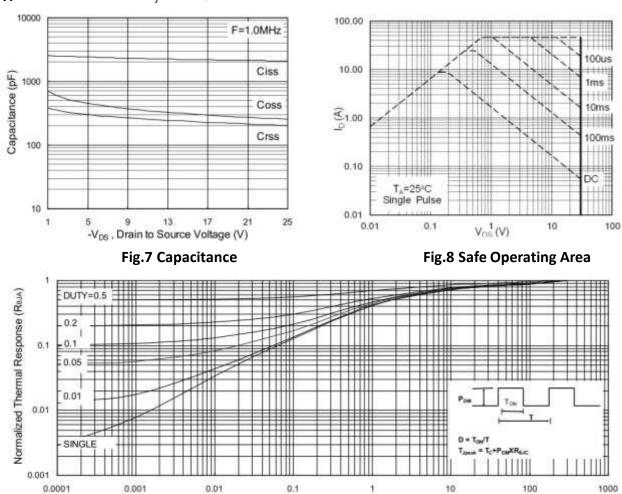


2.0

0.5



## **Typical Characteristics** $T_J = 25$ °C, unless otherwise noted



**Fig.9 Normalized Maximum Transient Thermal Impedance** 

4

t, Pulse Width (s)



Figure A: Gate Charge Test Circuit and Waveform

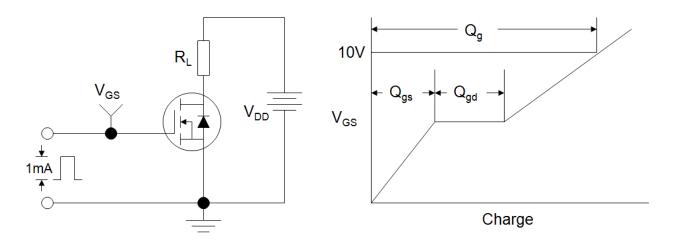


Figure B: Resistive Switching Test Circuit and Waveform

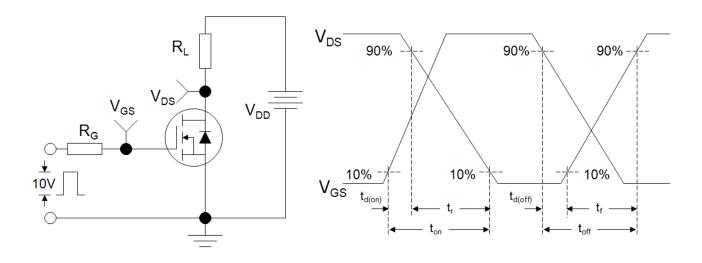
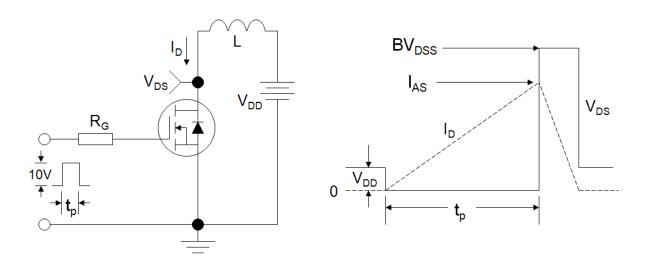
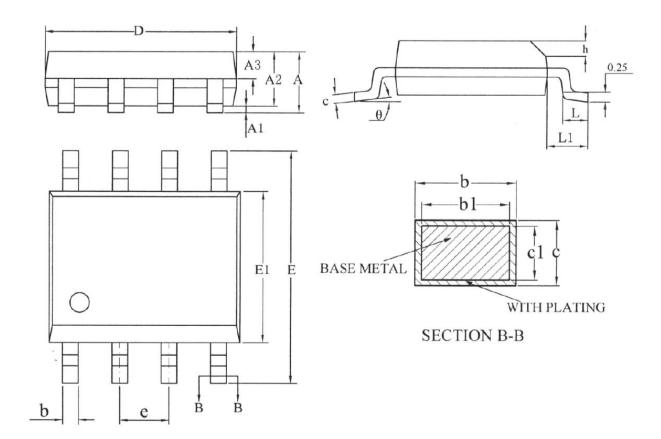


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# SOP-8



SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
A		_	1.75	
A1	0.10		0.225	
A2	1.30	1.40	1.50	
A3	0.60	0.65	0.70	
b	0.39		0.48	
b1	0.38	0.41	0.43	
С	0.21	_	0.26	
cl	0.19	0.20	0.21	

SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
D	4.70	4.90	5.10	
Е	5.80	6.00	6.20	
E1	3.70	3.90	4.10	
e	1.27BSC			
h	0.25	_	0.50	
L	0.50	_	0.80	
L1	1.05BSC			
е	0	_	8°	



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